25-06705

SY58603U



4.25Gbps Precision CML Buffer with Internal **Termination and Fail Safe Input**

General Description

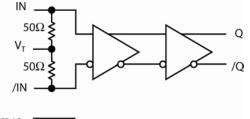
The SY58603U is a 2.5/3.3V, high-speed, fully differential CML buffer optimized to provide less than 10ps_{np} total jitter. The SY58603U can process clock signals as fast as 2.5GHz or data patterns up to 4.25Gbps.

The differential input includes Micrel's unique, 3-pin input termination architecture that interfaces to LVPECL, LVDS or CML differential signals, (AC-coupled or DCcoupled) as small as 100mV (200mVpp) without any level-shifting or termination resistor networks in the signal path. For AC-coupled input interface applications, an integrated voltage reference (V_{REF-AC}) is provided to bias the V_T pin. The output is 400mV CML, with extremely fast rise/fall times guaranteed to be less than 85ps.

The SY58603U operates from a 2.5V ±5% supply or 3.3V ±10% supply and is guaranteed over the full industrial temperature range (-40°C to +85°C). For applications that require LVPECL or LVDS outputs, consider the SY58604U and SY58605U, buffers with 800mV and 325mV output swings respectively. The SY58603U is part of Micrel's high-speed, Precision Edge[®] product line.

Data sheets and support documentation can be found on Micrel's web site at: www.micrel.com.

Functional Block Diagram





Features

- Precision 400mV CML buffer
- Guaranteed AC performance over temperature and voltage:
 - DC-to >4.25Gbps throughput _
 - <300ps propagation delay (IN-to-Q)
 - <85ps rise/fall times
- Fail Safe Input
 - Prevents output from oscillating when input is invalid
- Ultra-low jitter design
 - <1ps_{RMS} cycle-to-cycle jitter
 - <10ps_{PP} total jitter
 - <1ps_{RMS} random jitter
 - <10ps_{PP} deterministic jitter
- High-speed CML output
- 2.5V ±5% or 3.3V ±10% power supply operation
- Industrial temperature range: -40°C to +85°C
- Available in 8-pin (2mm x 2mm) DFN package

Applications

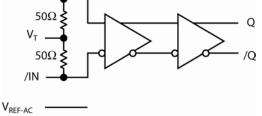
- Data Distribution: OC-48, OC-48+FEC, XAUI
- Backplane Buffering
- SONET clock or data distribution
- Fibre Channel clock or data distribution
- Gigabit Ethernet clock or data distribution

Markets

- Storage
- ATE
- Test and measurement
- Enterprise networking equipment
- High-end servers
- Access
- Metro area network equipment

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Ordering Information⁽¹⁾

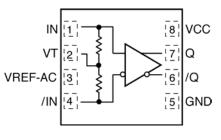
Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY58603UMG	DFN-8	Industrial	603 with Pb-Free bar-line indicator	NiPdAu Pb-Free
SY58603UMGTR ⁽²⁾	DFN-8	Industrial	603 with Pb-Free bar-line indicator	NiPdAu Pb-Free

Notes:

1. Contact factory for die availability. Dice are guaranteed at $T_A = 25^{\circ}C$, DC Electricals only.

2. Tape and Reel.

Pin Configuration



8-Pin DFN

Pin Description

Pin Number	Pin Name	Pin Function	
1, 4	IN, /IN	Differential Input: This input pair is the differential signal input to the device. Input accepts DC-Coupled differential signals as small as 100mV (200mVpp). Each pin of this pair internally terminates with 50Ω to the VT pin. If the input swing falls below a certain threshold (typical 30mV), the Fail Safe Input (FSI) feature will guarantee a stable output by latching the output to its last valid state. See "Input Interface Applications" section for more details.	
2	VT	Input Termination Center-Tap: Each side of the differential input pair terminates to VT pin. This pin provides a center-tap to a termination network for maximum interface flexibility. See "Input Interface Applications" section.	
3	VREF-AC	Reference Voltage: This output biases to V_{CC} –1.2V. It is used for AC-coupling inpu IN and /IN. Connect VREF-AC directly to the corresponding VT pin. Bypass with 0.01µF low ESR capacitor to VCC. Maximum sink/source current is ±1.5mA. Pleas refer to the "Input Interface Applications" section for more details.	
5	GND	Ground: Exposed pad must be connected to a ground plane that is the same	
	Exposed pad	potential as the ground pin.	
6, 7	/Q, Q	CML Differential Output Pair: Differential buffered output copy of the input signal. The output swing is typically 400mV. See "CML Output Termination" section.	
8	VCC	Positive Power Supply: Bypass with 0.1uF//0.01uF low ESR capacitors as close to the V_{CC} pin as possible.	

Absolute Maximum Ratings⁽¹⁾

Supply Voltage (V_{CC})
Current (V _T)
Source or sink on VT pin±100mA
Input Current
Source or sink Current on (IN, /IN)±50mA
Current (V _{REF})
Source or sink current on V _{REF-AC} ⁽⁴⁾ ±1.5mA
Maximum operating Junction Temperature
Lead Temperature (soldering, 20sec.)
Storage Temperature (T_s) 65°C to +150°C

Operating Ratings⁽²⁾

Supply Voltage (V _{IN})	+2.375V to +3.60V
Ambient Temperature (T _A)	
Package Thermal Resistance ⁽³⁾	
DFN	
Still-air (0,IA)	

Suii-aii (_{9JA})	95 0/11
Junction-to-board (ψ_{JB})	56°C/W

DC Electrical Characteristics⁽⁵⁾

 $T_A = -40^{\circ}C$ to +85°C, unless otherwise stated.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V _{CC}	Power Supply Voltage Range		2.375	2.5	2.625	V
			3.0	3.3	3.6	
Icc	Power Supply Current	No load, max. V _{CC}		39	50	mA
$R_{\text{DIFF}_{\text{IN}}}$	Differential Input Resistance (IN-to-/IN)		90 100		110	Ω
VIH	Input HIGH Voltage (IN, /IN)	IN, /IN, Note 7	V _{CC} -1.6		V _{cc}	V
VIL	Input LOW Voltage (IN, /IN)	IN, /IN	0		V _{IH} -0.1	V
V _{IN}	Input Voltage Swing (IN, /IN)	see Figure 3a, Note 6	0.1		1.7	V
$V_{\text{DIFF}_\text{IN}}$	Differential Input Voltage Swing (IN - /IN)	see Figure 3b	0.2			V
$V_{\text{IN}_{\text{FSI}}}$	Input Voltage Threshold that Triggers FSI			30	100	mV
V_{REF-AC}	Output Reference Voltage		V _{CC} -1.3	V _{cc} -1.2	Vcc-1.1	V
V_{T_IN}	Voltage from Input to V_T				1.28	V

Notes:

1. Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.

- 2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
- Package thermal resistance assumes exposed pad is soldered (or equivalent) to the device's most negative potential on the PCB. ψ_{JB} and θ_{JA} values are determined for a 4-layer board in still-air number, unless otherwise stated.
- 4. Due to the limited drive capability, use for input of the same package only.
- 5. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.
- 6. V_{IN} (max) is specified when V_T is floating.
- 7. V_{IH} (min) not lower than 1.2V.

CML Output DC Electrical Characteristics⁽⁷⁾

 V_{CC} = +2.5V ±5% or +3.3V ±10%, R_L = 100 Ω across the outputs; T_A = -40°C to +85°C, unless otherwise stated.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V _{OH}	Output HIGH Voltage	$R_L = 50\Omega$ to V_{CC}	V _{CC} -0.020	V _{CC} -0.010	V _{CC}	V
V _{OUT}	Output Voltage Swing	See Figure 3a	325	400		mV
V _{DIFF_OUT}	Differential Output Voltage Swing	See Figure 3b	650	800		mV
Rout	Output Source Impedance		45	50	55	Ω

Note:

7. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

AC Electrical Characteristics

 V_{CC} = +2.5V ±5% or +3.3V ±10%, R_L = 100 Ω across the outputs, Input t_r/t_f : <300ps; T_A = -40°C to +85°C, unless otherwise stated.

Symbol	Paramet	ter	Condition		Min	Тур	Max	Units
f _{MAX}	Maximur	m Frequency	NRZ Data		4.25			Gbps
			V _{OUT} > 200mV C	Clock	2.5	3		GHz
t _{PD}	Propagation Delay IN-to-Q		V _{IN} : 100mV-200mV		150	250	350	ps
			V _{IN} : 200mV-800mV		120	190	300	ps
t _{Skew}	Part-to-F	Part Skew	Note 8				100	ps
t _{Jitter}	Data	Random Jitter	Note 9				1	ps _{RMS}
		Deterministic Jitter	Note 10				10	ps _{PP}
	Clock	Cycle-to-Cycle Jitter	Note 11				1	ps _{RMS}
		Total Jitter	Note 12				10	ps _{PP}
t _{r,} t _f	Output F (20% to	Rise/Fall Times 80%)	At full output swing.		30	50	85	ps
	Duty Cycle		Differential I/O		47		53	%

Notes:

8. Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature and no skew at the edges at the respective inputs.

9. Random jitter is measured with a K28.7 pattern, measured at $\leq f_{MAX}$.

10. Deterministic jitter is measured at 2.5Gbps with both K28.5 and 2²³-1 PRBS pattern.

11. Cycle-to-cycle jitter definition: the variation period between adjacent cycles over a random sample of adjacent cycle pairs. $t_{JITTER_CC} = T_n - T_{n+1}$, where T is the time between rising edges of the output signal.

Total jitter definition: with an ideal clock input frequency of ≤ f_{MAX} (device), no more than one output edge in 10¹² output edges will deviate by more than the specified peak-to-peak jitter value.

Functional Description

Fail-Safe Input (FSI)

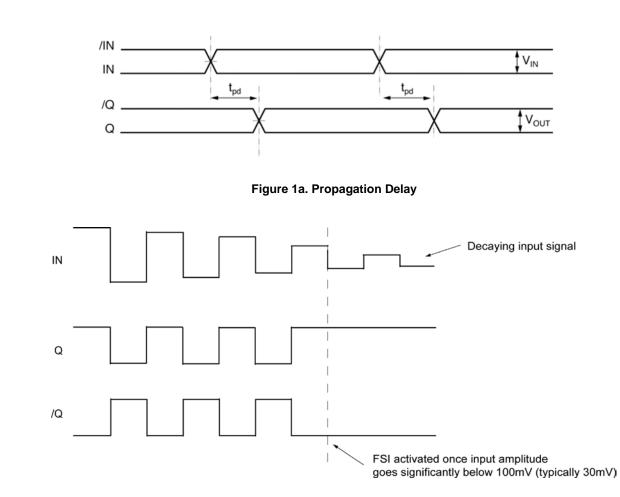
Timing Diagrams

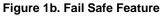
The input includes a special failsafe circuit to sense the amplitude of the input signal and to latch the output when there is no input signal present, or when the amplitude of the input signal drops sufficiently below $100mV_{PK}$ ($200mV_{PP}$), typically $30mV_{PK}$. Maximum frequency of SY58603U is limited by the FSI function.

Input Clock Failure Case

If the input clock fails to a floating, static, or extremely low signal swing, the FSI function will eliminate a metastable condition and guarantee a stable output. No ringing and no undetermined state will occur at the output under these conditions.

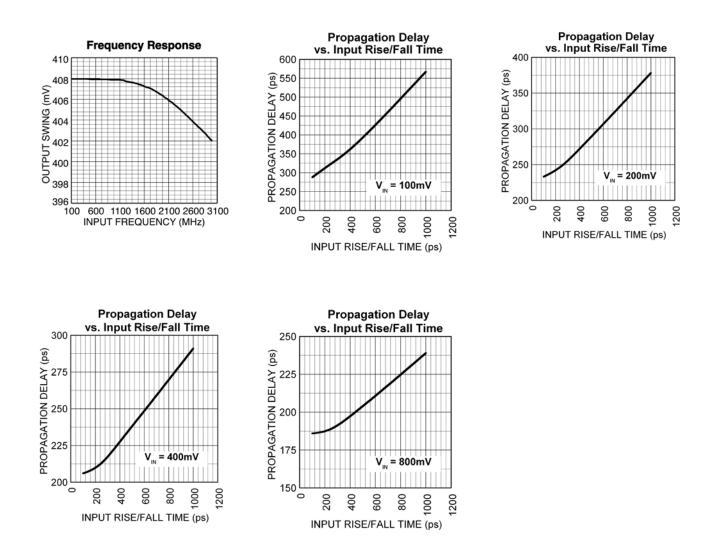
Note that the FSI function will not prevent duty cycle distortion in case of a slowly deteriorating (but still toggling) input signal. Due to the FSI function, the propagation delay will depend on rise and fall time of the input signal and on its amplitude. Refer to "Typical Characteristics" for detailed information.





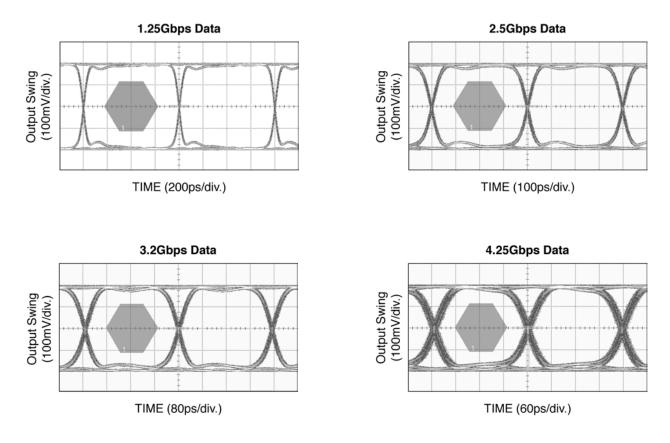
Typical Characteristics

 V_{CC} = 2.5V, GND = 0V, V_{IN} = 100mV, R_L = 100 Ω across the outputs, T_A = 25°C, unless otherwise stated.



Functional Characteristics

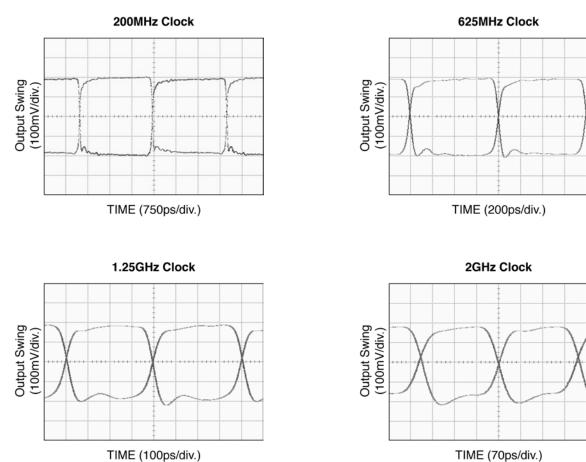
 V_{CC} = 2.5V, GND = 0V, V_{IN} = 325mV, Data Pattern: 2²³-1, R_L = 100 Ω across the outputs, T_A = 25°C, unless otherwise stated.



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Functional Characteristics (continued)

 V_{CC} = 2.5V, GND = 0V, V_{IN} = 325mV, R_L = 100 Ω across the outputs, T_A = 25°C, unless otherwise stated.



TIME (100ps/div.)

Input and Output Stage

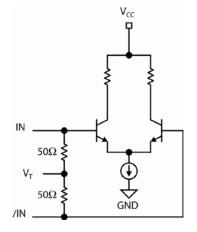


Figure 2a. Simplified Differential Input Buffer

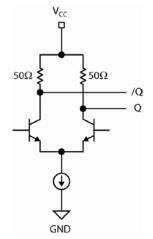


Figure 2b. Simplified CML Output Buffer

Single-ended and Differential Swings



Figure 3a. Single-Ended Swing

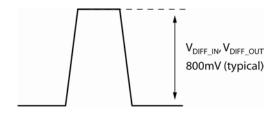


Figure 3b. Differential Swing

Input Interface Applications

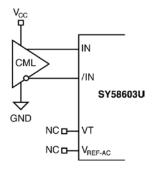
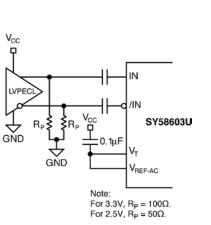
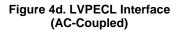


Figure 4a. CML Interface (DC-Coupled)

Option: May connect V_T to V_{CC}





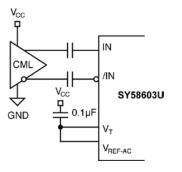


Figure 4b. CML Interface (AC-Coupled)

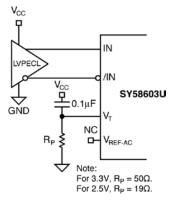


Figure 4c. LVPECL Interface (DC-Coupled)

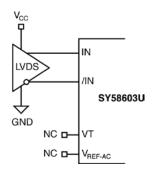
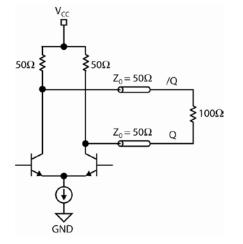


Figure 4e. LVDS Interface

CML Output Termination



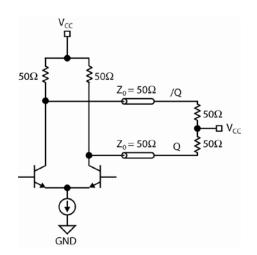
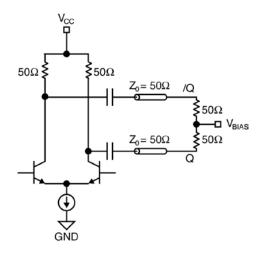


Figure 5a. CML DC-Coupled Termination



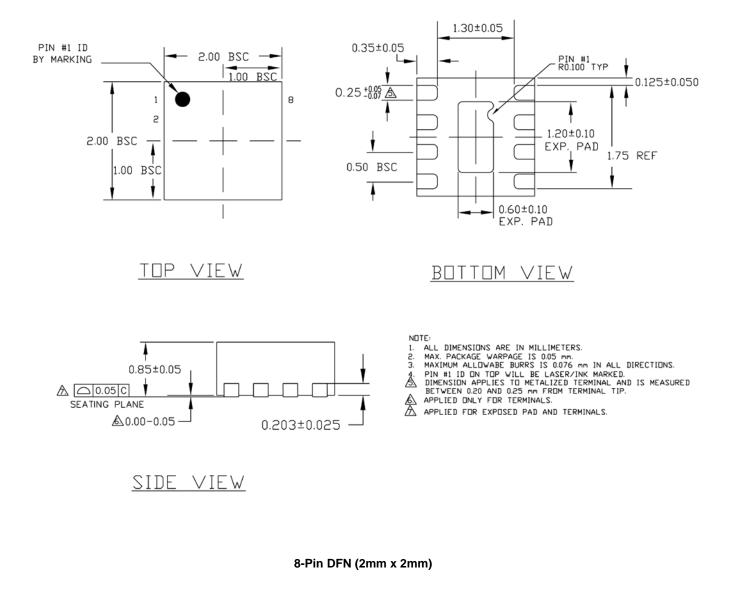




Related Product and Support Documents

Part Number	Function	Data Sheet Link		
SY58604U	3.2Gbps Precision LVPECL Buffer with Internal Termination and Fail Safe Input	http://www.micrel.com/page.do?page=/product- info/products/sy58604u.shtml		
SY58605U	3.2Gbps Precision LVDS Buffer with Internal Termination and Fail Safe Input	http://www.micrel.com/page.do?page=/product- info/products/sy58605u.shtml		
HBW Solutions	New Products and Termination Application Notes	http://www.micrel.com/page.do?page=/product- info/as/HBWsolutions.shtml		

Package Information



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